



TSMC Files Annual Report on Form 20-F for 2016

Hsinchu, Taiwan, R.O.C. – April 13, 2017 - TSMC (TWSE: 2330, NYSE: TSM), today filed its 2016 annual report on Form 20-F with the U.S. Securities and Exchange Commission.

The report is available at <http://www.tsmc.com/download/ir/secFillings/20F-2016.pdf>.

Hard copies of the report are also available, free of charge, upon request via <http://citibank.ar.wilink.com>.

About TSMC

TSMC is the world's largest dedicated semiconductor foundry, providing the industry's leading process technology and the foundry's largest portfolio of process-proven libraries, IPs, design tools and reference flows. The Company's owned capacity in 2017 is expected to reach above 11 million (12-inch equivalent) wafers, including capacity from three advanced 12-inch GIGAFAB® facilities, four eight-inch fabs, one six-inch fab, as well as TSMC's wholly owned subsidiaries, WaferTech and TSMC China. TSMC is the first foundry to provide both 20nm and 16nm production capabilities. Its corporate headquarters are in Hsinchu, Taiwan. For more information about TSMC please visit <http://www.tsmc.com>.

TSMC Spokesperson:

Lora Ho
Senior VP & CFO
Tel: 886-3-505-4602

TSMC Acting Spokesperson:

Elizabeth Sun
Senior Director
Corporate Communications
Division
Tel: 886-3-568-2085
Mobile: 886-988-937999
E-Mail: elizabeth_sun@tsmc.com

For Further Information:

Michael Kramer
Project Manager
PR Department
Tel: 886-3-563-6688
Ext. 7125031
Mobile: 886-988-931352
E-Mail: pdkramer@tsmc.com